

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6119xxxx7R-G
Typical Mass: 1 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.098	Silicon	98400	7440-21-3
	-	Arsenic	<1	7440-38-2
Lead pad	0.239	Nickel	239300	7440-02-0
	0.002	Gold	1500	7440-57-5
Die attach	0.008	Epoxy Resin	8100	—
	0.005	Acrylic Resin	4900	—
Bonding wire	0.050	Gold	50000	7440-57-5
Resin	0.523	Silica	523000	60676-86-0
	0.030	Epoxy Resin	29900	—
	0.027	Phenol Resin	26900	—
	0.018	Metal hydroxide	17900	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."